

AUSTIN TX 78729



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FILING DATE APPLICATION NO. FIRST NAMED INVENTOR ATTORNEY DOCKET NO. 8 11/22/99 POZDER SC10861TP 09/443.443 **EXAMINER** MM92/0802 ABBOTT, B HARRY A WOLIN MOTOROLA INC ART UNIT PAPER NUMBER AUSTIN INTELLECTUAL PROPERTY LAW SEC 7700 WEST PARMER LANE MD TX32 PL02 2823

DATE MAILED:

08/02/00

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

Office Action Summary

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Application No.

Applica...(s)

09/443,443 Examiner

Group Art Unit

2823

Pozder et al.



	Barbara Elizabeth Abbott	2823	
Responsive to communication(s) filed on			
☐ This action is FINAL .			
☐ Since this application is in condition for allowance exc in accordance with the practice under Ex parte Quay	ept for formal matters, prosecution was C.D. 11; 453 O.G. 213.	on as to the m	erits is closed
A shortened statutory period for response to this action is longer, from the mailing date of this communication. Fail application to become abandoned. (35 U.S.C. § 133). Example 1.136(a).	set to expire3 month(s)	esponse will ca	use the
Disposition of Claim			
		is/are pend	ding in the applicat
Of the above, claim(s) <u>12-23</u>			
Claim(s)			
X Claim(s) <u>1-11</u>			
Claim(s)			
☐ Claims			
Application Papers See the attached Notice of Draftsperson's Patent D The drawing(s) filed on	is approved is approved is approved is approved is approved is incirct, approved is approved in approv	een	
Attachment(s)			
 Motice of References Cited, PTO-892 Information Disclosure Statement(s), PTO-1449, Pa Interview Summary, PTO-413 Notice of Draftsperson's Patent Drawing Review, PT Notice of Informal Patent Application, PTO-152 			
SEE OFFICE ACTIO	ON ON THE FOLLOWING PAGES		

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Applicant's election with traverse of claims 1-11 in Paper No. 4 is acknowledged. The traversal is on the ground(s) that the examination of claims 1-23, method and device, would not be a burden on the examiner. This is not found persuasive because method and device have separate classifications. The examiner is not required to search both the method class (438) and the device class (257) when claims are drawn to one or the other.

The requirement is still deemed proper and is therefore made FINAL.

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 2 and 7 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. The term "mostly" in claim 2 is a relative term which renders the claim indefinite. The term "mostly" is not defined by the claim, the specification does not provide a standard for ascertaining the requisite degree, and one of ordinary skill in the art would not be reasonably apprised of the scope of the invention. If the applicant intends a particular atomic weight % in the conductive bond pad then it must be clearly recited. The term "low yield strength" in claim 7 is a relative term which renders the claim indefinite. The term "low yield strength" is not defined by the claim, the specification does not provide a standard for ascertaining the requisite degree, and

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one of ordinary skill in the art would not be reasonably apprised of the scope of the invention. If the applicant intends a particular yield strength or material it must be clearly recited.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless --

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1, 2, 3, 4, 5, and 10 are rejected under 35 U.S.C. 102(b) as being anticipated by Freeman, Jr. et al. (5,149,674).

Freeman, Jr. et al. disclose a method for forming a semiconductor device comprising forming a conductive bond pad (13/18) which can be made of copper having dielectric studs (14) formed therein over a semiconductor substrate (11); forming a dielectric layer (19) which can be made of a material selected from a group consisting of a nitride over (13/18); removing portions of (19); wherein removing portions of (19) forms a plurality of support structures that overlie (13/18) and are interconnected with unremoved portions of (19), and wherein at least a portion of a support structure overlies a portion of a dielectric stud, and wherein removing portions of (19) exposes a portion of (13/18); and forming a conductive capping layer (27) which can include aluminum overlying the plurality of support structure, wherein (27) electrically contacts a portion of (13/18). (Col. 3, line 19- Col. 5, line 14).

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The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 6 and 7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Freeman, Jr. et al. as applied to claims 1, 2, 3, 4, 5, and 10 above and further in view of Takiar et al. (4,723,197).

Freeman, Jr. et al. disclose that (13/18) is formed over a layer of silicon dioxide or any suitable dielectric. Freeman, Jr. et al. do not specifically disclose a dielectric layer having a Young's modulus less than approximately 50 Giga Pascals or having a low yield strength. Takiar et al. teach a method of forming a conductive bond pad including forming the bond pad over dielectric layers including silicon nitride, silicon oxynitride, polyimide, silicon nitride, and silicon dioxide. These materials are considered preferred materials in the instant application. (Col. 2, line 53- Col. 3, line 34). It would have been within the scope of one with ordinary skill in the art at the time of the invention to use the materials of Takiar et al. for their disclosed intended purpose in the process of Freeman, Jr. et al. to form the dielectric layer upon which the conductive bond pad is formed.

Claims 8 and 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Freeman, Jr. et al. as applied to claims 1, 2, 3, 4, 5, and 10 above, and further in view of White (5,942,448). Art Unit: 2823

Freeman, Jr. et al. do not disclose forming a barrier layer which includes a material selected from the group consisting of tantalum, titanium, tungsten, and chromium between the capping layer (27) and the conductive bond pad (13/18). White teaches forming a conductive bond pad (22) with a capping layer (26) with a barrier layer (24) disposed therebetween. (24) is made of titanium-tungsten. It would have been within the scope of one with ordinary skill in the art at the time of the invention to employ the process of White for its disclosed intended purpose and the material of White for its disclosed intended purpose in the step of forming the conductive bond pad of Freeman, Jr. et al.

Claim 11 is rejected under 35 U.S.C. 103(a) as being unpatentable over Freeman, Jr. et al. as applied to claims 1, 2, 3, 4, 5, and 10 above, and further in view of Hwang et al. (5,912,510).

Freeman, Jr. et al. do not disclose forming the conductive capping layer (27) from a material selected from the group consisting of nickel and palladium. Hwang et al. teach the suitability of using nickel to form a capping layer over a bond pad. (Col. 3, lines 8-25 and Fig. 2). It would have been within the scope of one with ordinary skill in the art to use the material of Hwang et al. for its disclosed intended purpose to form the capping layer of Freeman, Jr. et al.

Any inquiry of a general nature or relating to the status of this application should be directed to the Group Receptionist whose telephone number is (703) 308-0956. **See MPEP 203.08**.

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to examiner Barbara Elizabeth Abbott whose telephone number is (703) 306-5866. The examiner can normally be reached on Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (703) 308-4918. The fax number for this group is (703)308-7722(and 7724 and 7382). MPEP 502.01 contains instructions regarding procedures used in submitting responses by facsimile transmission.

George Fourson Primary Examiner Art Unit 2823

B.E.Abbott July 29, 2000